Bill Wu (Wei William Wu)

San Francisco Bay Area, USA | [billwu3018@gmail.com](mailto:billwu3018@gmail.com) | 415-630-3018 | U.S. Citizen | Available Immediately | Willing to Travel Internationally |

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# Professional Summary

Hardware Manufacturing Engineering Program Manager with 20+ years of global experience leading New Product Introduction (NPI), hardware build readiness, and cross- functional program execution across IoT, AIoT, telecom, and embedded systems. Proven record of managing 20+ complex hardware programs from concept through EVT/DVT/PVT to mass production. Adept at triaging technical issues, driving DOE/DFM improvements, coordinating with contract manufacturers, and ensuring supplier engineering performance. Skilled at aligning EE, ME, SW, TE, and operations teams to deliver products on time, on budget, and at scale. Holds a Ph.D. in Industrial Computing & Embedded Systems and fluent in English, Chinese, and French.

# Core Competencies

* End-to-End NPI & Build Coordination: EVT, DVT, PVT, MP, sustaining
* Cross-Functional Leadership: EE, ME, FW, ID, QA, Ops, TE
* DOE, DFM/DFX Reviews, Failure Analysis, Root Cause Resolution
* BOM Management: Cost optimization, supplier engagement, design change tracking
* Test Engineering & Fixture Development: Validation, calibration, yield improvement
* Supplier & CM Collaboration: Tooling readiness, SOP optimization, overseas vendor management
* Compliance & Reliability: NEBS, EMI/EMC, environmental/regulatory certifications
* Program Management: Risk tracking, issue escalation, executive reporting
* Logistics & Build Support: Overseas shipment coordination, sample inventory control

# Professional Experience

**IoT/AIoT Product Strategy Consultant -** Silicon Valley, USA | 2025 – Present

* Lead NPI programs for IoT/edge devices, managing design reviews, BOM readiness, and build schedules with ODM/JDM/CM vendors.
* Defined DOE and validation schedules, improving build readiness and reducing risk exposure.
* Coordinated EVT/DVT/PVT factory builds, ensuring fixture readiness, yield tracking, and issue resolution.
* Introduced structured risk frameworks and reporting dashboards, improving on- time delivery.

**CEO / Technical Program Lead** – Cynoware Electronics Inc. Nanjing, China | 2012 – 2025

* Directed 20+ IoT/AIoT hardware programs (POS, LTE routers, industrial tablets, SIP phones, smart mirrors) from concept → global deployment.
* Managed joint development with ODMs/CMs in Shenzhen, Suzhou, Xiamen, aligning build schedules and tooling, accelerating time-to-market by 25%.
* Oversaw mechanical design reviews, EE/FW integration, and compliance validation for large-scale deployments.
* Negotiated supplier contracts cutting BOM, while improving yields and reducing defects via DFM/DFX and stress testing.
* Established logistics and overseas shipment processes, managing sample inventory and factory readiness across Asia and Europe.

**Distinguished Professor (AIoT Applications)** - Hangzhou Dianzi University, China | 2017 – 2025

* Led academic–industry collaborations on embedded sensing, validation, and AIoT hardware systems.
* Directed international research projects applying IoT to real-time automation and predictive monitoring, advancing validation practices for manufacturing readiness.

**CTO** – Cynovo Electronics Inc. Wuxi, China | 2008 – 2012

* Launched China’s first industrial Android POS systems; owned HW/SW co-design, OS porting, driver integration, and mass production ramp-up.
* Collaborated with EMS partners to design test beds, optimize SOPs, and validate compliance.

**Sr. Technical Staff** – Turin Networks, Petaluma, CA, USA | 2000 – 2008

* Delivered carrier-grade telecom hardware with 99.999% uptime, supporting SONET/SDH, Ethernet, optical, and wireless.
* Developed device drivers for 30+ chipsets; provided APIs on VxWorks for flexible system integration.
* Directed NEBS/EMI validation and certification with Tier-1 global carriers.

# Education

* Ph.D. – Industrial Computing & Embedded Systems, Université de Lille, France
* M.S. & B.S. – Electrical Engineering, Wuhan University, China

# Languages

* English: Professional | Chinese: Native | French: Professional

# Selected Achievements

* End-to-End Delivery: Managed 20+ programs from requirements → MP with on- time delivery.
* DOE/DFM Excellence: Reduced field failure rates via structured DFM/DFX reviews and environmental stress testing.
* Supplier Leadership: Built long-term partnerships with ODMs/CMs in Asia, aligning build readiness and resolving production bottlenecks.
* BOM Optimization: Negotiated contracts achieving cost savings while improving component yield and quality.
* Global Engagement: Extensive travel across Japan, South Korea, Europe, U.S., and China to drive factory builds, supplier qualification, and compliance.

# Additional Information & Hobbies

* Willing to travel extensively for business and project-related work.
* Hiking and nature exploration enthusiast.